

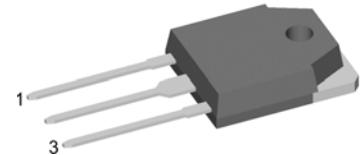
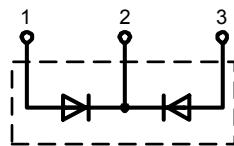
HiPerFRED

High Performance Fast Recovery Diode
Low Loss and Soft Recovery
Common Cathode

$V_{RRM} = 400 \text{ V}$
 $I_{FAV} = 2 \times 30 \text{ A}$
 $t_{rr} = 45 \text{ ns}$

Part number (Marking on product)

DPG 60 C 400QB

**Features / Advantages:**

- Planar passivated chips
- Very low leakage current
- Very short recovery time
- Improved thermal behaviour
- Very low I_{rm} -values
- Very soft recovery behaviour
- Avalanche voltage rated for reliable operation
- Soft reverse recovery for low EMI/RFI
- Low I_{rm} reduces:
 - Power dissipation within the diode
 - Turn-on loss in the commutating switch

Applications:

- Antiparallel diode for high frequency switching devices
- Antisaturation diode
- Snubber diode
- Free wheeling diode
- Rectifiers in switch mode power supplies (SMPS)
- Uninterruptible power supplies (UPS)

Package:

- TO-3P
- Industry standard outline - compatible with TO-247
 - Epoxy meets UL 94V-0
 - RoHS compliant

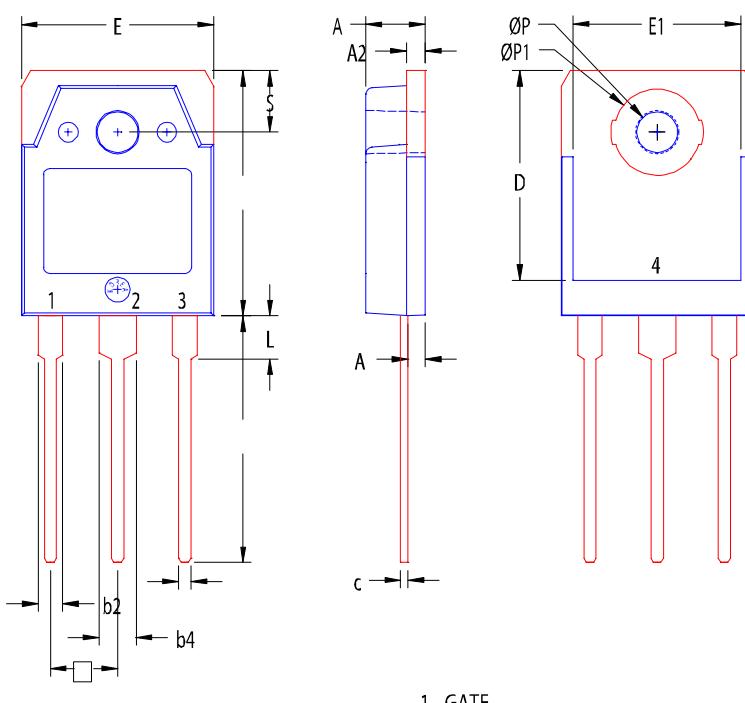
Ratings						
Symbol	Definition	Conditions	min.	typ.	max.	Unit
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25 \text{ }^\circ\text{C}$			400	V
I_R	reverse current	$V_R = 400 \text{ V}$ $T_{VJ} = 25 \text{ }^\circ\text{C}$ $V_R = 400 \text{ V}$ $T_{VJ} = 150 \text{ }^\circ\text{C}$			1	μA
V_F	forward voltage	$I_F = 30 \text{ A}$ $T_{VJ} = 25 \text{ }^\circ\text{C}$ $I_F = 60 \text{ A}$ $I_F = 30 \text{ A}$ $T_{VJ} = 150 \text{ }^\circ\text{C}$ $I_F = 60 \text{ A}$			1.41 1.69 1.13 1.46	V
I_{FAV}	average forward current	rectangular, $d = 0.5$			30	A
V_{FO} r_F	threshold voltage slope resistance	$\left. \begin{array}{l} \text{for power loss calculation only} \\ \text{ } \end{array} \right\}$	$T_{VJ} = 175 \text{ }^\circ\text{C}$		0.76	V
					10.7	$\text{m}\Omega$
R_{thJC}	thermal resistance junction to case				0.95	K/W
T_{VJ}	virtual junction temperature		-55		175	$^\circ\text{C}$
P_{tot}	total power dissipation				160	W
I_{FSM}	max. forward surge current	$t_p = 10 \text{ ms (50 Hz), sine}$			300	A
I_{RM}	max. reverse recovery current	$I_F = 30 \text{ A};$ $-di_F/dt = 200 \text{ A}/\mu\text{s}$		4		A
t_{rr}	reverse recovery time	$V_R = 100 \text{ V}$		45		ns
		$T_{VJ} = 25 \text{ }^\circ\text{C}$ $T_{VJ} = 125 \text{ }^\circ\text{C}$				ns
C_J	junction capacitance	$V_R = 200 \text{ V}; f = 1 \text{ MHz}$			30	pF
E_{AS}	non-repetitive avalanche energy	$I_{AS} = 9 \text{ A}; L = 100 \mu\text{H}$			0.5	mJ
I_{AR}	repetitive avalanche current	$V_A = 1.5 \cdot V_R \text{ typ.; } f = 10 \text{ kHz}$			0.9	A

Symbol	Definition	Conditions	Ratings			
			min.	typ.	max.	
I_{RMS}	RMS current	per pin*			50	A
R_{thCH}	thermal resistance case to heatsink			0.25		K/W
M_D	mounting torque		0.8		1.2	Nm
F_c	mounting force with clip		20		120	N
T_{stg}	storage temperature		-55		150	°C
Weight				5		g

* I_{RMS} is typically limited by: 1. pin-to-chip resistance; or by 2. current capability of the chip.

In case of 1, a common cathode/anode configuration and a non-isolated backside, the whole current capability can be used by connecting the backside.

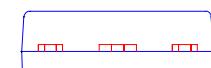
Outlines TO-3P



SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.185	.193	4.70	4.90
A1	.051	.059	1.30	1.50
A2	.057	.065	1.45	1.65
b	.035	.045	0.90	1.15
b2	.075	.087	1.90	2.20
b4	.114	.126	2.90	3.20
c	.022	.031	0.55	0.80
D	.780	.791	19.80	20.10
D1	.665	.677	16.90	17.20
E	.610	.622	15.50	15.80
E1	.531	.539	13.50	13.70
e	.215	BSC	5.45	BSC
L	.779	.795	19.80	20.20
L1	.134	.142	3.40	3.60
ØP	.126	.134	3.20	3.40
ØP1	.272	.280	6.90	7.10
S	.193	.201	4.90	5.10

- 1 - GATE
- 2 - DRAIN (COLLECTOR)
- 3 - SOURCE (EMITTER)
- 4 - DRAIN (COLLECTOR)

All metal area are tin plated.



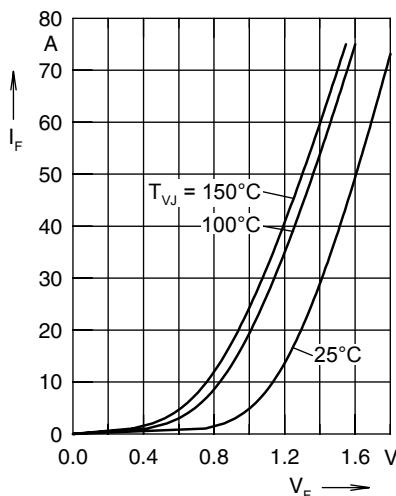
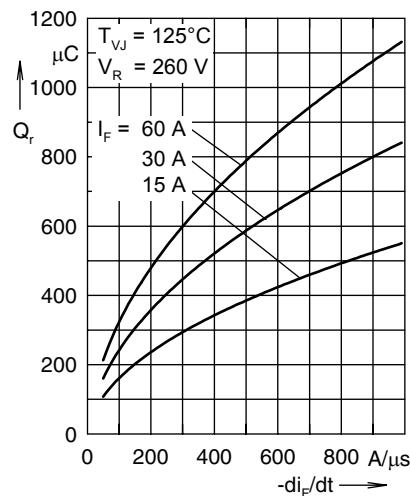
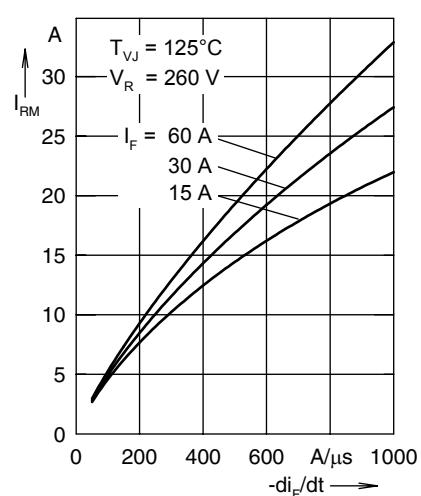
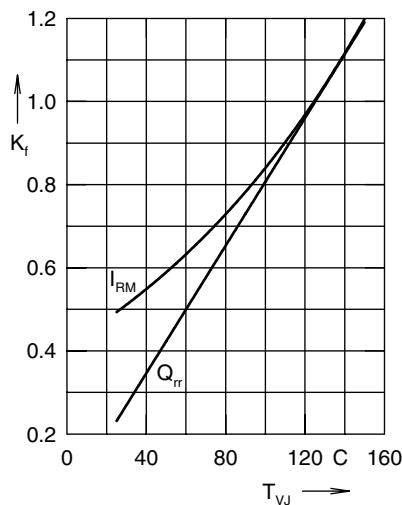
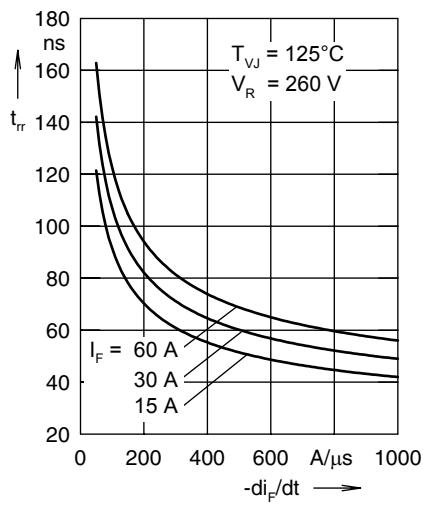
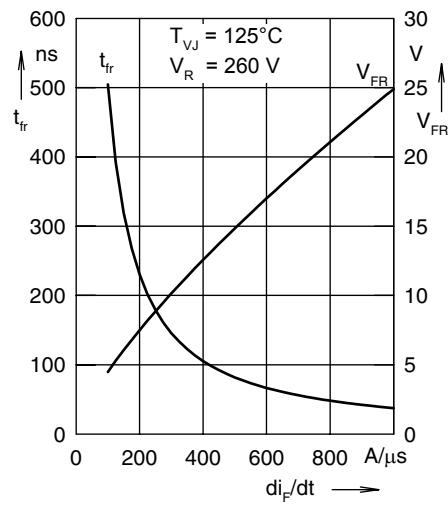
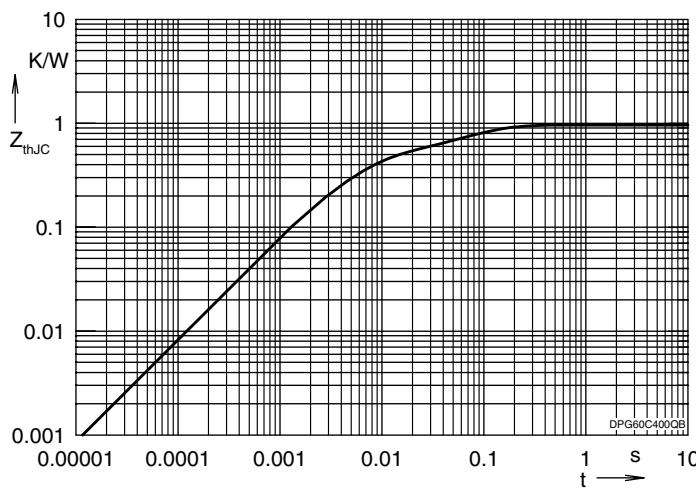
Fig. 1 Forward current I_F vs. V_F Fig. 2 Typ. reverse recovery charge Q_r versus $-di_F/dt$ Fig. 3 Typ. peak reverse current I_{RM} versus $-di_F/dt$ Fig. 4 Dynamic parameters Q_{rr} , I_{RM} versus T_{VJ} Fig. 5 Typ. recovery time t_{rr} vs. $-di_F/dt$ Fig. 6 Typ. peak forward voltage V_{FR} and t_{fr} versus di_F/dt 

Fig. 7 Transient thermal impedance junction to case